



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-10-25
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	Anto ella Lanzafame	Representative title	AMSMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
TSB181IYDT	3D07*UBHL1AY	A	BO2A	2024-10-25
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	80	mg	Each	ECOPACK® 3
Identity	Authority			
Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony			

Manufacturing information			
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles	
1	260	3	
Bulk solder termination	Terminal plating	Terminal base alloy	Comment
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0

Package designator	Package size	Number of instances	Shape
DSO	4.85x3.9	8	gull wing
Comment			
Comment	07 SO 08 .15 JEDEC		

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020	Response
1 - Product(s) meets EU ELV requirements without any exemptions	true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Exemption Id.	Description

QueryList : California Prop65 list, dated 17th Nov 2023	Response		
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen	true		
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen	false		
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.000	alloy	0

QueryList :Customer	Response
QUERY	Response

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014	Response			
QUERY	Response			
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products	false			
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products	false			
Hazardous substance				
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE
0	0	0	0	0

QueryList : REACH-27th June 2024	Response			
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	true			
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material



QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Gold, Tin,

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	true
All the adhesive impacted complies with GB 33372	true

QueryList:Stockholm Convention Persistent Organic Pollutants (POP)	Response
Product is compliant with Annex A, B and C of Stockholm Convention Persistent Organic Pollutants	true

QueryList: EU Ship Recycling Regulation No. 1257/2013	Response
Product contains hazardous materials listed in Annex II of EU Ship Recycling Regulation No.1257/2013 and 2009/16/EC Directive	False

PFAS/PTFE Declaration	Response
The product is containing at least one of the following PFAS substance: Polytetrafluoroethylene,Thiophenium, Triphenylsulfonium nonaflate, Trifluoroacetic anhydride	False

BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document							Mfr Item Name	3D07UBHL1AY		80.0000		5999997.0	1000006.0
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Die	M-011 Other inorganic materials	1.193	mg	supplier	die	Silicon(Si)	7440-21-3		1.136	mg	952221	14200	
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.011	mg	9220	138	
				supplier	metallisation	Copper(Cu)	7440-50-8		0.002	mg	1676	25	
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.001	mg	838	13	
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.003	mg	2515	38	
				supplier	passivation	Silicon oxide	7631-86-9		0.028	mg	23470	350	
				supplier	polymer coating	polyimide	proprietary		0.012	mg	10059	150	
Leadframe	M-004 Copper and its alloys	29.189	mg	supplier	alloy	Copper(Cu)	7440-50-8		27.986	mg	958786	349825	
				supplier	alloy	Iron(Fe)	7439-89-6		0.658	mg	22543	8225	
				supplier	alloy	Iron phosphide	1310-43-6		0.040	mg	1370	500	
				supplier	alloy	Zinc(Zn)	7440-66-6		0.035	mg	1199	438	
				supplier	metallization	Silver(Ag)	7440-22-4		0.470	mg	16102	5875	
				supplier	glue	Silver(Ag)	7440-22-4		0.154	mg	875000	1925	
Die attach	M-011 Other inorganic materials	0.176	mg	supplier	glue	Isobornyl Methacrylate	7534-94-3		0.009	mg	51136	113	
				supplier	glue	Isobornyl acrylate	5888-33-5		0.009	mg	51136	113	
				supplier	glue	Methyl acrylate polymer	87320-05-6		0.004	mg	22727	50	
				supplier	wire	Gold(Au)	7440-57-5		0.065	mg	1000000	813	
Bonding wires	M-008 Precious metals	0.065	mg	supplier	wire	Gold(Au)	7440-57-5		0.065	mg	1000000	813	
Encapsulation	M-011 Other inorganic materials	48.659	mg	supplier	mold compound	Silica vitreous	60676-86-0		34.840	mg	716003	435500	
				supplier	mold compound	Silicon oxide	7631-86-9		7.299	mg	150003	91238	
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		3.649	mg	74991	45613	
				supplier	mold compound	Phenol resin	26834-02-6		2.433	mg	50001	30413	
				supplier	mold compound	Carbon black	1333-86-4		0.243	mg	4994	3038	
				supplier	mold compound	Bismuth compound	7440-69-9		0.195	mg	4007	2438	
Connections coating	Solder	0.718	mg	supplier	solder alloy	Tin(Sn)	7440-31-5		0.718	mg	1000000	8975	